

SID

Factory: Rot am See

Article:

ML6

Provided:

Customer:

Date:

03.04.2026

WÜRTH  
ELEKTRONIK  
MORE THAN  
YOU EXPECT

Processtechnology: B: undefined

Material Text	Mat. Nr.	µm	Stackup	Process overview
A-RS Kupferfolie-035my 330x490mm	50200242	35	VS	1
C-RAS-FR4-PP-2116-H53-TG150-HF-EM-37B...	50203001	429		2
C-RAS-FR4-PP-7628-TG150HF-gel-PAN-R15...	50202586	0		3
C-RAS-FR4-PP-2116-H53-TG150-HF-EM-37B...	50203001	0		4
		35	L2	
B-RaS-FR4-DS-0.991mm-035+035-TG150-HF...	50203141	920		5
		35	L3	
C-RAS-FR4-PP-1080-H63-TG150-HF-EM-37B...	50203000	247		6
C-RAS-FR4-PP-2116-H53-TG150-HF-EM-37B...	50203001	0		7
C-RAS-FR4-PP-1080-H63-TG150-HF-EM-37B...	50203000	0		8
		35	L4	
B-RaS-FR4-DS-0.991mm-035+035-TG150-HF...	50203141	920		9
		35	L5	
C-RAS-FR4-PP-2116-H53-TG150-HF-EM-37B...	50203001	429		10
C-RAS-FR4-PP-7628-TG150HF-gel-PAN-R15...	50202586	0		11
C-RAS-FR4-PP-2116-H53-TG150-HF-EM-37B...	50203001	0		12
A-RS Kupferfolie-035my 330x490mm	50200242	35	RS	13

B00:

A01

A02

Thickness after Pressing

B00:

3090 µm

Tol+:

320 µm

Tol-:

320 µm

Dmax:

3410 µm

Dmin:

2770 µm

Thickness over all

0 µm

Tol+:

0 µm

Tol-:

0 µm

Dmax:

0 µm

Dmin:

0 µm

Demand for customer

Thickness (D):

3200 µm

Tol+:

320 µm

Tol-:

320 µm

Dmax:

3520 µm

Dmin:

2880 µm

Measuring point: (05) over SM and galv. Cu; both sides

nominal:

3155 µm

Version 1.2.20.35

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